

Chip Scale Review®

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The Future of Semiconductor Packaging

2019 Editorial Calendar

<i>(Editorial close date: 6/15)</i>	July • August	Industry Events * indicates show distribution
High reliability materials		<ul style="list-style-type: none"> • ICEPT 2019 Shanghai, China (Aug 11-15) • SEMICON Taiwan * Taipei, Taiwan (Sept 18-20) • European MEMS & Sensors Summit Grenoble, France (Sept 19-21) • European Imaging & Sensors Summit Grenoble, France (Sept 19-21)
Metal-based wafer-level and 3D printed packaging		
Temporary bonding for high temperature processing of thin glass		
Chip-package-board co-design		
Coaxial socket technology		
MEMS & Sensors		
Large-area fan-out processing		

Ad Space Close Jun 30 - Ad Materials Close Jul 7

<i>(Editorial close date: 7/20)</i>	September • October	Industry Events * indicates show distribution
Effective, Scalable EMI Protection		<ul style="list-style-type: none"> • SMTA International * Rosemont, IL (October 24-25) • IWLPC-International Wafer-Level Packaging Conference & Exhibition * San Jose, CA (Oct 22-24) • IMPACT Taipei, Taiwan (October 24-26) • TestConX China 2019 Suzhou, China (Oct 23) Shenzhen, China (Oct 25) • International Test Conference (ITC) Phoenix, AZ (Oct 28- Nov 2) • SEMI International Technology Partners Conference (ITPC) Maui, Hawaii (Nov 4-7) • SEMICON Europa / Productronica Munich, Germany (Nov 12-16)
Embedded RDL		
High density flip-chip and advanced CSP		
High-resolution 3D X-ray metrology		
Advanced substrates and embedded packaging		
High density advanced packaging (HDAP) design		
Direct-placement process for LED's		
Inspection strategies		
High density advanced packaging design		

Ad Space Close Sep 8 - Ad Materials Close Sep 15

<i>(Editorial close date: 9/21)</i>	November • December	Industry Events * indicates show distribution
Collective bonding for heterogeneous integration		<ul style="list-style-type: none"> • EPTC 2019 * Singapore (Dec 3-6) • MEPTEC: Heterogeneous Integration Symposium Milpitas, CA (TBD) • SEMICON Japan Tokyo, Japan (Dec 11-13) • SEMI European 3D Summit * Dresden, Germany (TBD) • SEMICON Korea 2020 Coex, Seoul, Korea (Feb 5-7, 2020)
Cooling solutions for hi-density chips		
Advanced eWLB for mmWave applications		
High temperature survivability & the processes it allows		
Package assembly design kits		
Integration		
Direct-placement process LED's		
TSV and RDL technologies, the road ahead		

Ad Space Close Nov 3 - Materials Close Nov 10

For ad inquiries: ads@chipscalereview.com - For editorial inquiries editor@chipscalereview.com

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